

- NOTES (UNLESS OTHERWISE SPECIFIED)
1. USING SUPPLIED CAD DATA.
  2. MATERIAL: STANDARD FR4 LAMINATE AND PREPREG
  3. COPPER WEIGHT SHALL BE 0.5 OZ PLATED TO 1 OZ CU
  4. ALL HOLES SHALL BE LOCATED WITHIN 0.005 IN DIAMTER OF TRUE POSITION LAYER TO LAYER REGISTRATION SHALL BE WITHIN .005 IN
  5. FINISH  
ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED BY SOLDERMASK SHALL PLATED WITH ELECTROLESS NICKEL IMMERSOIN GOLD (ENIG)  
APPLY LPI PHOTO IMAGEABLE SOLDER MASK (COLOR GREEN) TO BOTH SIDES OVER BARE COPPER
  6. THE TOTAL NUMBER OF CONDUCTOR LAYERS IS 2 AND THE OVERALL THICKNESS OF THE PCB AFTER PLATING SHALL BE 0.062 MIL +/- 10%
  7. ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPEN/SHORTS USING THE PROVIDED IPC-365 NETLIST
  8. WARP AND TWIST OF BOARD SHALL NOT EXCEED 1%
  9. CONDUCTOR WIDTHS AND SPACINGS SHALL BE WITHIN .001 INCH OF SUPPLIED CAD DATA

